

规格书编号

SPEC NO :

# 产品规格书

# SPECIFICATION

CUSTOMER 客户: \_\_\_\_\_

PRODUCT 产品: \_\_\_\_\_ SAW FILTER \_\_\_\_\_

MODEL NO 型号: \_\_\_\_\_ HDF110L2-F11 \_\_\_\_\_

PREPARED 编制: \_\_\_\_\_ CHECKED 审核: \_\_\_\_\_

APPROVED 批准: \_\_\_\_\_ D A T E 日期: \_\_\_\_\_ 2012-3-31 \_\_\_\_\_

客户确认 CUSTOMER RECEIVED:		
审核 CHECKED	批准 APPROVED	日期 DATE

无锡市好达电子有限公司  
Shoulder Electronics Limited



## 1. SCOPE

This specification shall cover the characteristics of SAW filter F110L2.

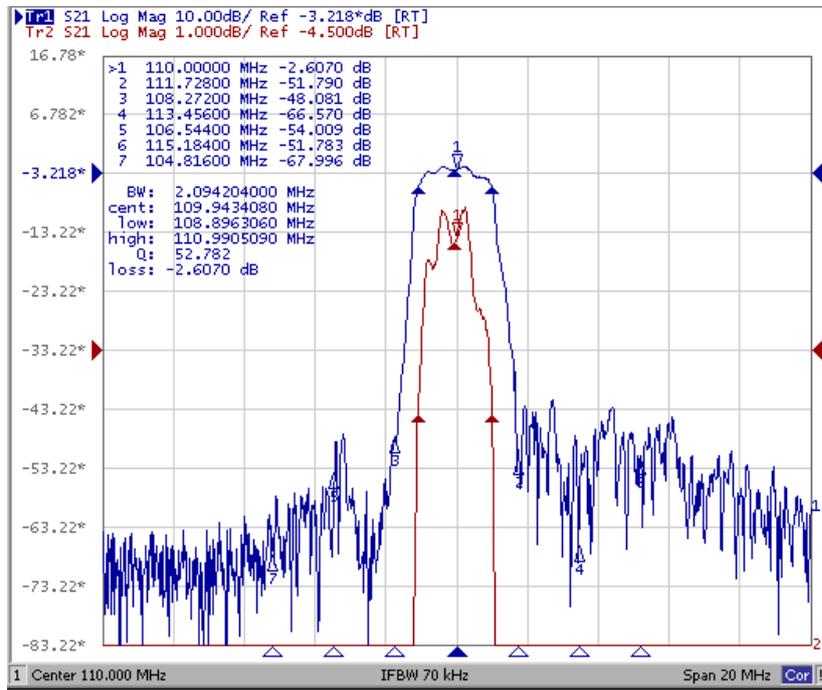
## 2. ELECTRICAL SPECIFICATION

DC Voltage VDC	10V
AC Voltage Vpp	10V50Hz/60Hz
Operation temperature	-40°C to +85°C
Storage temperature	-45°C to +85°C
RF Power Dissipation	0dBm

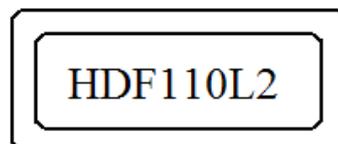
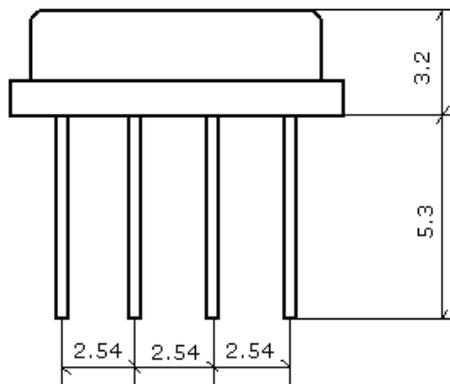
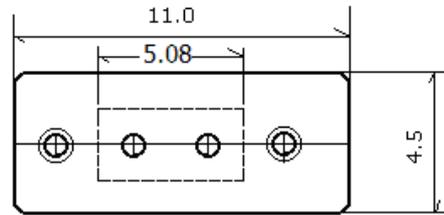
### 2.2 Electronic Characteristics

型号 Part Number	HDF110L2
中心频率(fo)(MHz) Nominal Center Frequency	110.000
3dB 带宽 Bandwidth(from fo)(KHz)	+/-576min
阻带衰减 Stop Band Attenuation (from peak level)(dB) 1)fo-3×1.728MHz 2)fo-2×1.728MHz 3)fo+/-1.728MHz 4)fo+2×1.728MHz 5)fo+3×1.728MHz	50min 45min 30min 40min 40min
插入损耗(dB) Insertion Loss(at minimum loss point)	4.5max
群延时波动(fo+/-576KHz)(μscc.) Group Delay Deviation	0.7
输入/输出阻抗 Input/output Impedance	300 Ω //1.2 μ H

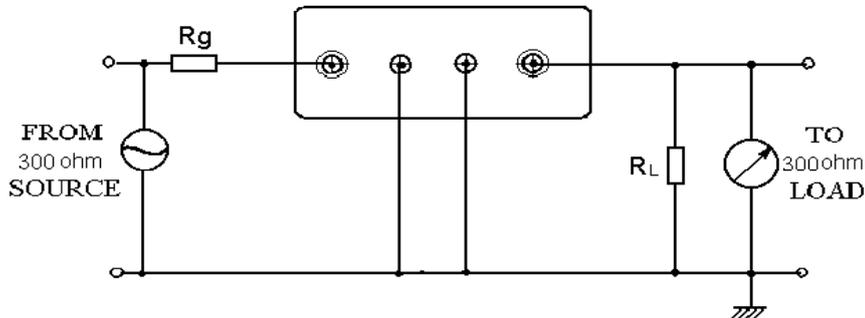
**Typical frequency response**



**3. DIMENSION**



## 4. TEST CIRCUIT



## 5. ENVIRONMENTAL CHARACTERISTICS

### 5-1 High temperature exposure

Subject the device to +85 °C for 16 hours. Then release the filter into the room conditions for 24 hours prior to the measurement. It shall fulfill the specifications in 2.2.

### 5-2 Low temperature exposure

Subject the device to -40 °C for 16 hours. Then release the device into the room conditions for 24 hours prior to the measurement. It shall fulfill the specifications in 2.2.

### 5-3 Temperature cycling

Subject the device to a low temperature of -40 °C for 30 minutes. Following by a high temperature of +85 °C for 30 Minutes. Then release the device into the room conditions for 24 hours prior to the measurement. It shall meet the specifications in 2.2.

### 5-4 Resistance to solder heat

Dip the device terminals no closer than 1.5mm into the solder bath at 260 °C  $\pm$  10 °C for 10  $\pm$  1 sec. Then release the device into the room conditions for 4 hours. The device shall meet the specifications in 2.2.

### 5-5 Solderability

Subject the device terminals into the solder bath at 245 °C  $\pm$  5 °C for 5s, More than 95% area of the terminals must be covered with new solder. It shall meet the specifications in 2.2.

### 5-6 Mechanical shock

Drop the device randomly onto the concrete floor from the height of 1m 3 times. the device shall fulfill the specifications in 2.2.

### 5-7 Vibration

Subject the device to the vibration for 1 hour each in x,y and z axes with the amplitude of 1.5 mm at 10 to 55 Hz. The device shall fulfill the specifications in 2.2.

## **6. REMARK**

### 6.1 Static voltage

Static voltage between signal load & ground may cause deterioration & destruction of the component. Please avoid static voltage.

### 6.2 Ultrasonic cleaning

Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning

### 6.3 Soldering

Only leads of component may be soldered. Please avoid soldering another part of component.